

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : TBD Confirmation No.: TBD
Applicant : Jeffrey A. West et al.
Filed : 10/30/2003
TC/A.U. : TBD
Examiner : TBD

Docket No. : TI-36238
Customer No. : 23494

Title : METHOD FOR IMPROVING RELIABILITY OF COPPER
INTERCONNECTS

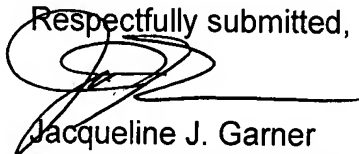
INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P. O. Box 1450
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Dear Sir:

Please make the references listed on the enclosed PTO-1449 of record under 37 C.F.R. 1.56, 1.97, and 1.98 in the patent application identified above. Copies of the listed references are enclosed.

Respectfully submitted,


Jacqueline J. Garner
Attorney for Applicants
Reg. No. 36,144

Texas Instruments Incorporated
P. O. Box 655474, MS 3999
Dallas, Texas 75265
(214) 532-9348 or (972) 917-5643
(972)917-4418 Fax

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				Complete If Known	
				Application Number	TBD
				Filing Date	10/30/2003
				First Named Inventor	Jeffrey A. West
				Group Art Unit	TBD
				Examiner Name	TBD
Sheet	1	of	1	Attorney Docket No.	TI-36238

U.S. PATENT DOCUMENTS						
Exam. Initials*	Cite No. ¹	U.S. Patent Document		Name of Patentee or Applicant of Cited Doc.	Date of Pub. of Cited Doc. (mm-yyyy)	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS			
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	CA	T. TAKEWAKI et al., "Excellent Electro/Stress-Migration-Resistance Giant-Grain Copper Interconnect Technology for High-Performance Power Devices," Proceedings of 1995 International Symposium on Power Semiconductor Devices & ICs, Yokohama, pp. 438-442.	
	CB	S. HYMES et al., "Passivation of copper by silicide formation in dilute silane," <i>J. Appl. Phys.</i> 71 (9), 1 May 1992, pp. 4623-4625.	
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